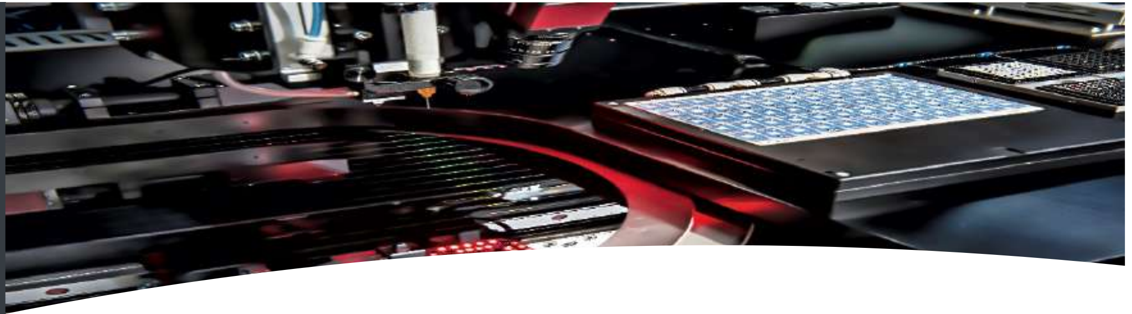
TRESKY
AUTOMATION



T-8000-G

- Best bonding performance in the market
- Designed for tomorrow´s semiconductor needs
- One machine, unlimited bonding processes
- Made in Germany

The T-8000-G DIE Bonder combines precision with customization.

It is build on a bigger granite gantry to combine space with the highest level of bonding accuracy.

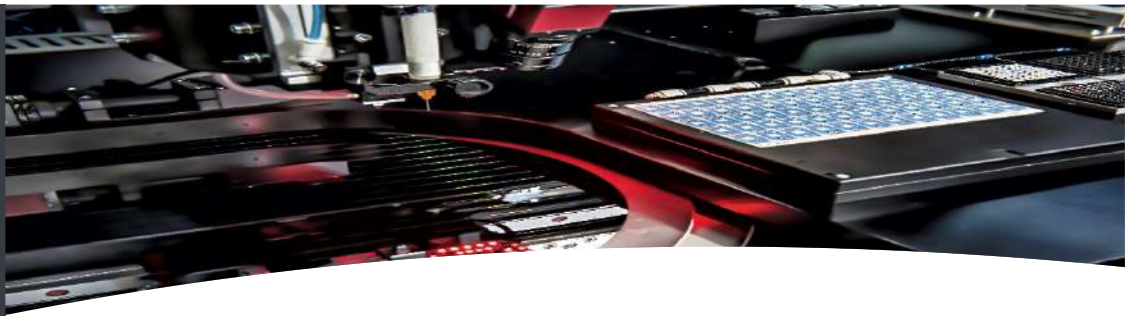
The ultimate bonding platform from prototyping to volume production.

Unique manual mode for instant DIE bonding.

Technical Data

Travel Range with Wafer	590 mm x 560 mm
Wafer Size	2” – 12” (Ring & Frame)
Travel Range w/o Wafer	740 mm x 560 mm
Z-Movement	120 mm
Chip Rotation max.	up to 360°
Bond Force Range	10 g – up to 10.000 g *
Axis Speed	up to 1.8 m/sec
Placement Accuracy	2.5 µm @ 3 sigma
Axis Resolution	XYZ: 0.01 µm, Theta: 0.01°
Min./Max. component size	80 µm – 100 mm **

* Higher bond force on request
** Other dimensions on request | Note: All specifications are subject to change without notice



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DIE Attach Technologies

- Micro Assembly
- Eutectic Bonding
- Stamping
- Ultrasonic Bonding
- Flip Chip Bonding
- Thermosonic Bonding
- Thermocompression Bonding
- Flux Dipping
- Adhesive Bonding
- DIE Stacking

Applications (Customer Specific)

- DTF / DAF Bonding
- Multi DIE Bonding
- MEMS
- SMD Bonding
- 3D Packaging (SiP)
- Laser Bar Stacking
- Glas Frit Bonding
- TO Header Bonding
- Vcsel Bonding
- RFID Assembly
- DIE Sorting

Modules & Options

- Wafer Table with DIE Ejector
- UV Indexer
- WRGB Light
- Heating Plates
  -Up to 450°C
  -Ramp rates up to 60 K/s
- Inert Gas Protection
- Automatic Tool Change
- Several Dispensing Options
- Stamping Unit
- Tool Heating
- Feeder Unit
- Uplooking Camera
- ID Scanner
- DIE Flipping Unit
- Pre-heated Inert Gas
- Automatic Wafer Change
- Conveyor / Magazine Lifter
- Inline Production

Features

- Manual Mode
- Multichip Application Capability
- Post Bond Inspection
- Software integrated temp. Control
- Wafer Mapping
- OCR
- Traceability
- MES
- Automatic Dispense Needle Calibration
- Customer Specific Workspace
- Scrubbing
- Pattern Recognition Methods
- Deep Access Bonding (15mm)
- Preform Cutter

For more informations:

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For more information about our products or services please visit or website www.tresky.de